

WHAT IS CLAIMED IS:

1. A package for enclosing a semiconductor chip comprising:
a plurality of terminals; and
one or more conductive members connecting the terminals to each other in a manner that the electrical connection is disabled by an action of mounting the package on a printed circuit board.
2. The package of claim 1, wherein the terminals include solder balls, and wherein the conductive members are formed of solder and are melted when the package is mounted on a printed circuit board by soldering the terminals.
3. The package of claim 2, wherein the conductive members are solder lines.
4. The package of claim 2, wherein the conductive members are a conductive thin film .
5. The package according to claim 1, wherein the terminals are pin-shaped having protruding tips; and wherein the conductive members are conductive wires connected at the tips of the terminals that are cut when the package is mounted on a printed circuit board by inserting the terminals into sockets.
6. A method for preventing electrostatic damages to a semiconductor chip package during storage, the package having a plurality of terminals, the method comprising:
forming one or more conductive members electrically connecting the terminals to each other; and
disabling the electrical connections by an action of mounting the package on a printed circuit board.
7. The method of claim 6, wherein the step of forming the conductive members comprises forming solder members connecting the terminals, and wherein the action of mounting the package comprises soldering the terminals.

8. The method of claim 7, wherein the step of forming the conductive members comprises forming solder lines connecting the terminals.

9. The method of claim 7, wherein the step of forming the conductive members comprises forming a conductive thin film.

10. The method of claim 6, wherein the terminals are pin-shaped having protruding tips, and the step of forming the conductive members comprises forming conductive wires connected at the tips of the terminals, and wherein the action of mounting the package comprises inserting the terminals into sockets.